

# ABSTRACT

A photosensitive resin composition according to the present invention includes at least a base resin component (A) and a (meth)acryls compound (B), wherein the base resin component (A) is any one of: a polyimide resin (A-1) having at least either a hydroxyl group or a carboxyl group in its structure; a polyamide resin (A-2) having at least either a hydroxyl group or a carboxyl group in its structure; and photosensitive imide (meth)acrylsiloxaneoligomer (A-3). On this account, it is possible to realize characteristics such as (1) realization and improvement of water system developing property, (2) improvement of utility as an imidized film, (3) improvement of post-curing property, and (4) simplification of manufacture of a print wiring substrate. Thus, the photosensitive resin composition can be favorably used particularly in a photosensitive dry film resin, a laminate using the same, a print wiring substrate using the same, and the like.